

located near each other for wire-bonding so that identical integrated-circuit chips are used to provide the dual-die, double-sized, back-to-back integrated-circuit chip assembly;

applying an external voltage to a bonding-option wire-bonding-pad to indicate whether the integrated-circuit chip is to provide a standard pattern for the reversible wire-bonding-pads, or alternatively, whether the integrated-circuit chip is to provide a reversed path for the reversible wire-bonding-pads; and

sensing the voltage applied to the bonding-option wire-bonding-pad for alternatively generating either a standard NRO gate control signal or a non-standard, reversed RO gate control signal from the voltage state of the bonding-option wire-bonding-pad.

#### CANCEL CLAIM 46

#### REMARKS

#### THE OFFICE ACTION MAILED APRIL 24, 2003

Claims 43-45 and 48 were rejected as being anticipated by a Golwalkar et al. US Patent No. 5,545,992. Claims 46-47 were objected to but would be allowable if rewritten in independent form. Claims 49-62 were said to be allowable.

#### DISCUSSION:

Independent Claim 43 is amended under current Rule 121 practice to include the allowable subject matter of Claim 46. Claim 46 is cancelled. Applicant respectfully requests reconsideration of the Amended Claims. All claims currently in the application are believed to be in condition for allowance and an early allowance would be appreciated.

Previously Applicant's attorney had attempted to provide an Amendment under the Voluntary Revised Practice and received a Notice of Non-Compliance with the Voluntary Revised Amendment Practice with a comment that a complete listing of all of the claims was not present in the previously submitted amendment paper. Applicant's attorney hereby requests withdrawal of the submission under the voluntary program and submits the instant amendment within the three month shortened statutory period required in the Office Action mailed April 24, 2003.